

Jaguar

High Performance Strip Test Handler



Automotive



Mobile



IoT/IoV & Optoelectronics

Productivity

- Fastest index time:
 - Strip down to 2.0 sec
 - Device down to 180 ms
- MUBA >1,000 strips >12 hr operation without assist possible
- Closed loop temperature conditioning of contactor embedded control sensor

Flexibility

- Tri-temp range -45°C to +160°C
- Extremely fast and easy kit conversion with quick lock function
- Stacked and slotted loader / unloader
- In process test due to SMEMA interface

Smart Factory Automation

- DI-Core Data Intelligence System provides real-time equipment monitoring and data analytics for Industry 4.0/Factory Automation
- Factory Automation with Industrial Mobile Robot (IMR) communicates via SECS-GEM and requires no additional connecting hardware (E84 Standard)
- Options for both Loader/Unloader types and field upgrade possible



Computing



Industrial



Consumer

- Ultrafast and precise plunger
- Handling of InCarrier Carrier
- Simple device kit exchange in <15 mins with existing kit recipe set-up
- High parallel power upgrade
- Bare die test configuration
- Various MEMS and sensor options

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Specifications

Platform

Performance Characteristics

- Strip index time down to 2.0 sec
- Device index time down to 0.18 sec
- MTBF: > 1,000 hr, MTTR: < 30 min, MTBA: > 4 hr
- Jam Rate < 1: 1,000 strips

Strip Dimensions

- Length: 76.2 mm to 300 mm
- Width: 25.4 mm to 102 mm
- Thickness: 1.0 mm (max.)
- Body height: 6 mm (max.)
- Devices per strip: 5,000 (max.)
- Strip warpage: ≤ 7 mm (max.)

Temperature Characteristics

- Range: -45°C to +160°C
- Accuracy: ±2°C
- Time to temp⁽¹⁾: 30 min (typ.)
- Soak capacity: 3 strips

Facility Requirements

- Nominal supply voltage⁽²⁾: 208 - 230 VAC
- Standard air pressure: 5.5 bar (80 psi)
- Air consumption⁽³⁾: 100 to 450 l/min
- LN₂ pressure: > 1.5 bar (22 psi), for cold test
- LN₂ consumption: 12l/h
- CDA dew point: ≤ -70°C

ESD Protection

- Field strength at device: 100 Volt/in (max.)
- Ground strap jack: 1 M-Ohm to ground
- Device path: conductive and grounded

(1) Ambient (+25°C) to set point.

(2) 3 x 16 A or 1 x 25 A, 50/60 Hz.

(3) Maximum consumption at hot operation.

All specifications are subject to change without notification and are for reference only. For detailed performance specifications, please contact Cohu.

Physical Dimensions (Width x Depth x Height)

- Basic handler: 1,200 x 830 x 1,040 mm
- Handler with slotted cassette modules:
 - 2,400 x 1,000 x 1,225 mm
- Handler with stacked cassette modules:
 - 2,000 x 830 x 1,040 mm

Electrical Interfaces

- RS 232 standard, IEEE 488
- Network standard, USB at OPI (standard)
- Strip mapping: SECS/GEM and XML, SEMI G84/G85, E142

Contactors or Probe Cards

- Nearly unlimited range for substrate based bare dies, WLP's or molded ICs
- Smart power, analog, RF, mixed signal, digital MEMS and KGD contactors are available

Optional Modules

- Stacked or slotted loader/unloader
- High Parallel Power (HPP)
- Various sensor test applications available

Advanced Configurations

Advanced Packaging / Bare Die Test Configuration

- 3D package test
- Substrate based, bare die handling
- Vacuum contacting
- Single device in a carrier or strip handling

Various Sensor and MEMS Options

- Magnetic Test Unit
- Pressure Test Unit